

Am90CL257

Low-Power 256K x 1 CMOS Static Column Mode DRAM

Am90CL257

OVERVIEW

The 256K x 1 CMOS Low-Power ('L') DRAM versions share common functional descriptions, DC and AC characteristics with the corresponding standard CMOS (non-'L') versions. The only additions to these sections are:

DISTINCTIVE CHARACTERISTICS

- Extended refresh period
 - 32 ms (Max.) during standby
- Low data retention current
 - 230 μ A (Max.)
- Low-power dissipation
 - 0.55 mW (Max.)

ORDERING INFORMATION

The Ordering Information for the Low-Power DRAM versions are the same as for the Standard CMOS DRAMs, with the exception of an 'L' inserted within the device number to denote 'Low-Power.' For example, the Am90CL255 is a 256K x 1 CMOS "Low-Power" Nibble Mode DRAM. All temperature ranges, speed and package options remain the same as those listed in Ordering Information sections for the respective Standard CMOS DRAMs.

DC CHARACTERISTICS

The low-power version DRAMs are screened for one additional parameter, viz, CMOS standby current. All other DC characteristics remain the same for both families.

Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Units
I _{CC6}	V _{CC} Supply Current CMOS Standby	$\overline{RAS} \geq V_{CC} - 0.5$ V and \overline{CAS} at V _{IH} , all other inputs and outputs $\geq V_{SS}$	Am90CL257		0.1	mA

The Am90CL257-15 is screened for I_{CC1} = 55 mA, I_{CC3} = 55 mA, and I_{CC4} = 55 mA.

AC CHARACTERISTICS

AC Characteristics remain unchanged on the low-power 100 ns and 120 ns versions. The AC characteristics corresponding to the 150 ns speed are on the following page.

FUNCTIONAL DESCRIPTION

The Functional Descriptions for low-power versions are the same as the corresponding standard versions. The low-power devices, however, support Extended Refresh cycles described below:

Extended Refresh Cycle

All low-power versions extend the Refresh Cycle period to 32 ms for \overline{RAS} -Only Refresh cycles. This feature reduces the total current consumption to a maximum of 230 μ A for data retention. The low-standby current can significantly extend battery life in battery back-up applications. Current consumption is calculated from the following equation:

$$I = \frac{(t_{RC}) (I_{ACTIVE}) + (t_{RI} - t_{RC}) (I_{STANDBY})}{T_{RI}}$$

where t_{RC} = Refresh Cycle Time

and t_{RI} = Refresh Interval Time or t_{REF}/256

Before entering or leaving an Extended Refresh period, the entire array must be refreshed at the normal interval of 4 ms. This can be accomplished by either a burst or distributed refresh.

4

SWITCHING CHARACTERISTICS ($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$ unless otherwise noted)

No.	Parameter Symbol	Parameter Description	Am90CL257-15		Units
			Min.	Max.	
READ/WRITE/READ-MODIFY-WRITE AND REFRESH CYCLES					
1	t_{RAS}	RAS Pulse Width	150	75,000	ns
2	t_{RC}	Random R/W Cycle Time	245		ns
3	t_{RP}	RAS Precharge Time	85		ns
4	t_{CSH}^*	\overline{CS} Hold Time	150		ns
5	t_{WRP}	Write-to-RAS Precharge Time	0		ns
6	t_{ASR}	Row Address Setup Time	0		ns
7	t_{RAH}	Row Address Hold Time	15		ns
8	t_{AR}	Column Address Hold Time from RAS	130		ns
9	t_{RHZ}	RAS-to-Output High Impedance (Note 1)		20	ns
10	t_{RLZ}	RAS-to-Output Low Impedance (Note 1)	30		ns
11	t_{HZ}^*	\overline{CS} -to-Output High Impedance (Notes 1 & 2)		25	ns
12	t_{LZ}^*	\overline{CS} -to-Output Low Impedance (Notes 1 & 2)			
13	t_{REF}	Time Between Refresh		4	ms
14	t_T	Transition Time (Rise and Fall) (Note 3)	3	50	ns
READ CYCLE					
15	t_{RAC}	Access Time From RAS (Notes 4 & 5)		150	ns
16	t_{CAC}^*	Access Time From \overline{CS} (Note 5)		30	ns
17	t_{CAA}	Access Time from Column Address (Note 5)		65	ns
18	$t_{CS(R)}^*$	\overline{CS} Pulse Width (Read Cycle)	30		ns
19	$t_{RSH(R)}^*$	RAS Hold Time (Read Cycle)	10		ns
20	t_{RCS}^*	Read Command Setup Time	0		ns
21	t_{CAR}	Column Address-to-RAS Setup Time	65		ns
22	t_{RCH}^*	Read Command Hold Time Referenced to \overline{CS}	0		ns
23	t_{RRH}	Read Command Hold Time Referenced to RAS	10		ns
24	t_{ARH}	Column Address Hold Time Referenced to RAS	0		ns
25	t_{RAD}	RAS-to-Column Address Delay Time (Note 6)	20	85	ns
26	$t_{CS(W)}^*$	\overline{CS} Pulse Width (Write Cycle)	30		ns
27	$t_{RSH(W)}^*$	RAS Hold Time (Write Cycle)	30		ns
WRITE CYCLE					
28	t_{WDR}	RAS-to-Write Command Delay Time	20		ns
29	t_{RWL}	Write Command to RAS Lead Time	30		ns
30	t_{CWL}^*	Write Command to \overline{CS} Lead Time	30		ns
31	t_{WP}	Write Command Pulse Width	30		ns
32	t_{WCP}	Write Command Precharge Time	10		ns
33	t_{WCS}^*	Write Command Setup Time	0		ns
34	t_{WCH}^*	Write Command Hold Time	30		ns
35	t_{WCR}	Write Command Hold Time from RAS	120		ns
36	t_{AWS}	Column Address-to-Write Command Setup Time	0		ns
37	t_{AWH}	Column Address-to-Write Command Hold Time	25		ns
38	t_{DS}	Data-In Setup Time	0		ns
39	t_{DH}	Data-In Hold Time	25		ns
40	t_{OW}	Output Active from End of Write	0		ns

*This parameter not applicable if operated with \overline{CS} grounded.
Notes: See next page for notes.

SWITCHING CHARACTERISTICS

($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$ unless otherwise noted)

No.	Parameter Symbol	Parameter Description	Am90CL257-15		Units
			Min.	Max.	
READ-MODIFY-WRITE (RMW) CYCLE					
41	t_{RWC}	RMW Cycle Time	280		ns
42	t_{RRW}	RMW Cycle $\overline{\text{RAS}}$ Pulse Width	185	75,000	ns
43	t_{CRW}^*	RMW Cycle $\overline{\text{CS}}$ Pulse Width	65		ns
44	t_{WRH}	$\overline{\text{WE}}$ -to- $\overline{\text{RAS}}$ Hold Time	5		ns
45	t_{RWD}	$\overline{\text{RAS}}$ -to- $\overline{\text{WE}}$ Delay Time (Note 7)	150		ns
46	t_{AWD}	Column Address-to- $\overline{\text{WE}}$ Delay Time (Note 7)	75		ns
47	t_{CWD}	$\overline{\text{CS}}$ -to- $\overline{\text{WE}}$ Delay Time (Note 7)	30		ns
STATIC COLUMN MODE CYCLE					
48	t_{OHA}	Output Hold Time from Address Change	10		ns
49	t_{OHW}	Output Hold Time from End of Write	0		ns
50	t_{WPA}	RMW Write Precharge Access Time		75	ns
51	t_{WRA}	RMW Write-Read Access Time		110	ns
52	t_{WPS}	RMW Write Command Precharge Time	75		ns

*This parameter not applicable if operated with $\overline{\text{CS}}$ grounded.

Notes: 1. Assumes three-state test load (5 pF and a 380 Ω Thevenin equivalent).

2. At any given temperature and voltage combination, t_{HZ} (Max.) is less than t_{LZ} (Min.) from device to device.

3. t_T is measured between V_{IH} (Min.) and V_{IL} (Max.).

4. Assumes that $t_{RAD} \leq t_{RAD}$ (Max.). If $t_{RAD} > t_{RAD}$ (Max.), then t_{RAC} will increase by the amount that t_{RAD} exceeds to t_{RAD} (Max.).

5. Load = 2 TTL loads and 100 pF.

6. t_{RAD} specified for reference only.

7. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are specified as reference points only. If $t_{WCS} \geq t_{WCS}$ (Min.), the cycle is an Early Write Cycle and the data-out pin will remain in high impedance for the duration of $\overline{\text{WE}}$. If $t_{WCD} \geq t_{CWD}$ (Min.) and $t_{AWD} \geq t_{AWD}$ (Min.), then the cycle is a Read-Modify-Write Cycle and the data-out will contain the data read from the selected address. If any of the above conditions are not satisfied, data-out is indeterminate.

8. Access time from a write command to a determined by the latter of t_{CAA} or t_{WPA} or t_{WRA} .